

ABSTRACT OF THE DISCLOSURE

POSITIVE-TYPE PHOTSENSITIVE RESIN COMPOSITION

Disclosed is a positive-type photosensitive resin composition comprising: (a) an alkali-soluble resin; (b) a quinone diazide compound; (c) a heatsensitive compound which colors upon being heated and which shows an absorption maximum at a wavelength of not less than 350 nm and not more than 700 nm; and
5 (d) a compound which does not have an absorption maximum at a wavelength of not less than 350 nm to less than 500 nm, and has an absorption maximum at a wavelength of not less than 500 nm and not more than 750 nm. The composition is preferably used for forming light-blocking separators or black matrices of organic
10 electroluminescent devices and liquid crystal display elements.

(FIG. 1)